



Material Content Data Sheet



Sales Product Name		ICE2QR1765		Issued		27. September 2017		
MA#		MA000980956						
Package		PG-DIP-8-13		Weight*		557.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.779	0.68	0.68	6783	6783
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7712	
wire	non noble metal	copper	7440-50-8	174.475	31.32	32.14	313156	321350
	noble metal	gold	7440-57-5	0.263	0.05	0.05	472	472
	encapsulation	organic material	carbon black	1333-86-4	1.093	0.20		1962
encapsulation	plastics	epoxy resin	-	35.340	6.34		63431	
	inorganic material	silicondioxide	60676-86-0	327.900	58.84	65.38	588530	653923
leadfinish	non noble metal	tin	7440-31-5	7.590	1.36	1.36	13622	13622
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1428	1428
glue	plastics	epoxy resin	-	0.202	0.04		363	
	noble metal	silver	7440-22-4	1.147	0.21	0.25	2059	2422
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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